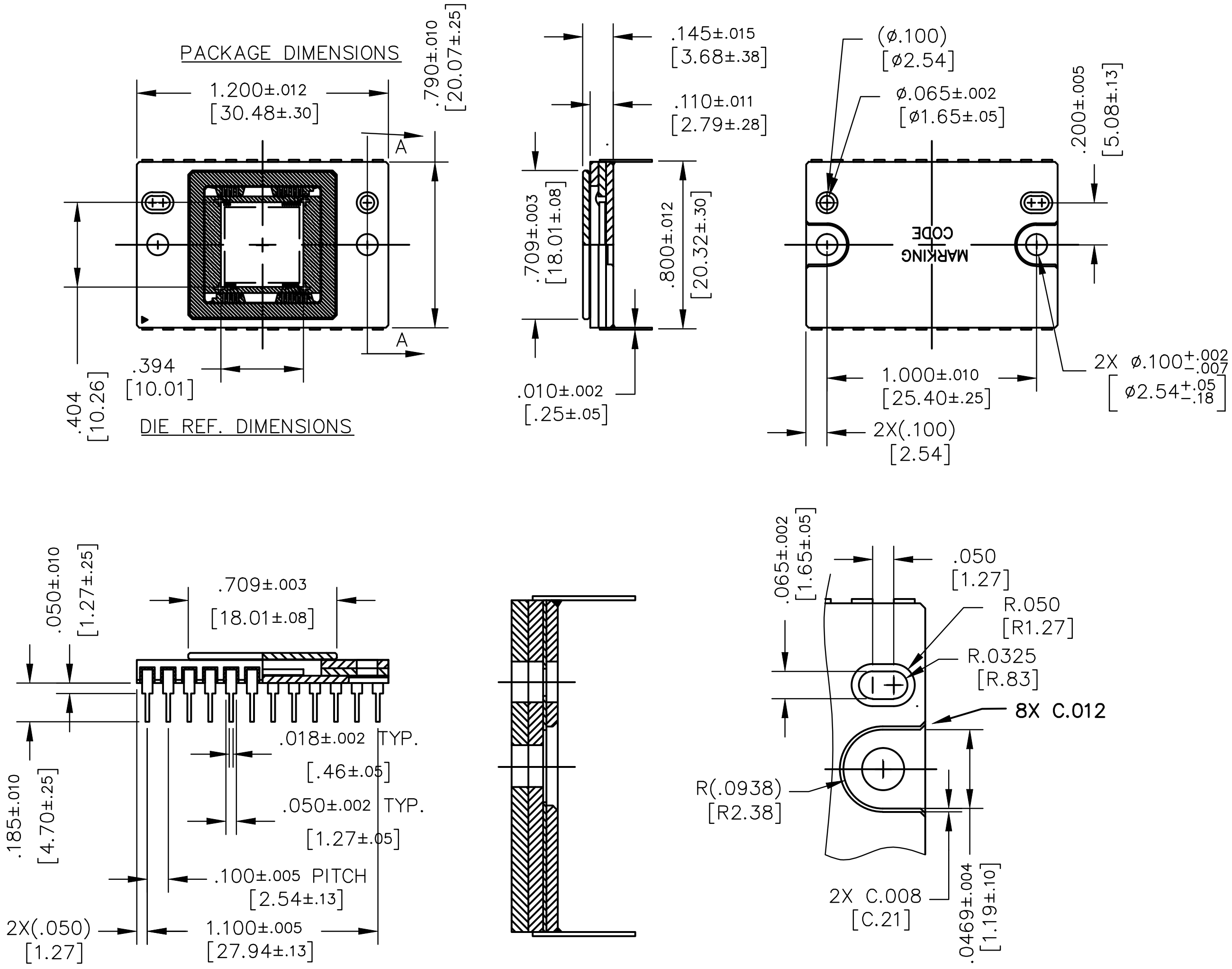
CERAMIC DIP 24
CASE 125AT
ISSUE O

DATE 30 JUN 2014



SECTION A–A

Notes:
1. Cover glass is manually placed and visually aligned over die – Location accuracy is not guaranteed.

Dimensions in: Inches [mm]

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DESCRIPTION:	**CERAMIC DIP 24**		**PAGE 1 OF 2**

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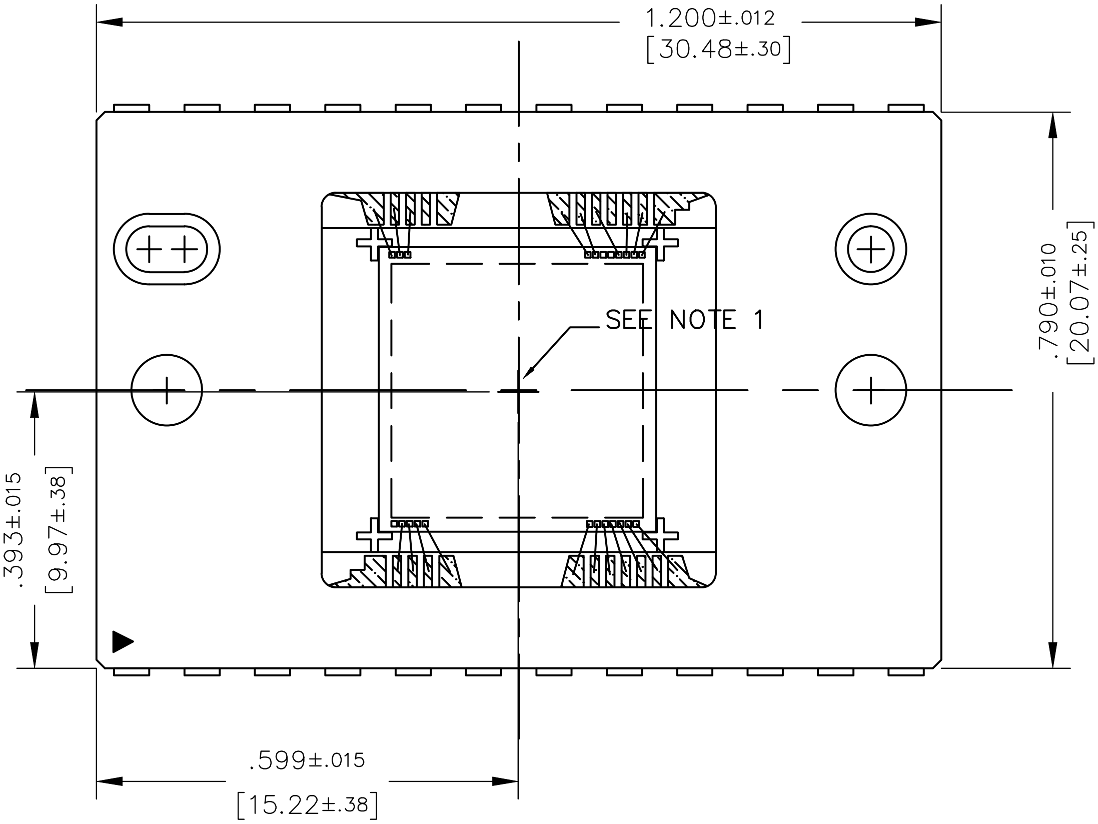

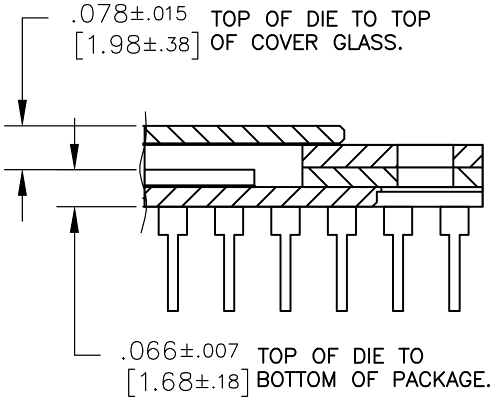

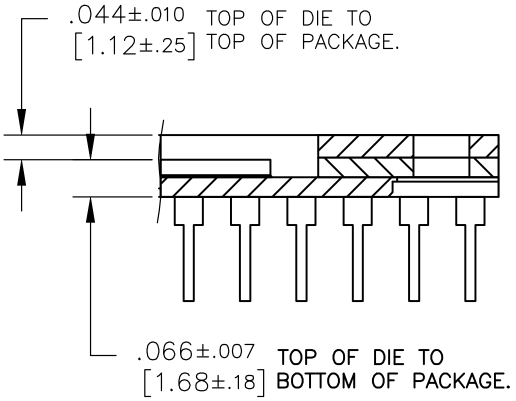

NOTES:
1. CENTER OF IMAGE AREA IS OFFSET FROM CENTER OF PACKAGE BY (−0.02,−0.06)MM NOMINAL.
2. DIE IS ALIGNED WITHIN +/− 2 DEGREE OF ANY PACKAGE CAVITY EDGE.

Dimensions in: Inches [mm]

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